

ICVISP 2026

2026 10th International Conference on Vision Image and Signal Processing

December 11-13, 2026 | Haikou, China

2026年第十届视觉、图像与信息信号处理国际会议

Welcome to ICVISP 2026

It is with great pleasure that we invite you to the 2026 10th International Conference on Vision, Image and Signal Processing (ICVISP 2026), which is organized by Hainan University, and is scheduled to take place from December 11-13, 2026, in Haikou, China.

ICVISP is committed to delivering a platform for collaboration and discovery, with the aim of driving progress in image, vision, and signal processing—key technologies that are enhancing our understanding of the world and propelling advancements in artificial intelligence, machine learning, and a multitude of other applications that are transforming industries and improving lives.

We warmly invite your contributions and eagerly anticipate the opportunity to meet with you in person at ICVISP 2026.

Organizing Committee

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Xianpeng Wang, Hainan University, China
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Topics of Interest

For more information, please visit: www.icvisp.org/cfp.html

Computer Vision

- 3D Computer Vision
- Adversarial Attack and Defense
- Deep Learning Architectures and Techniques
- Document Analysis and Understanding

Image Processing

- Synthesis, Rendering, & Visualization
- Computational Imaging
- Restoration & Enhancement
- Image & Video Quality Models

Signal Processing

- Applied Signal Processing Systems
- Audio & Acoustic Signal Processing
- Biomedical Imaging & Signal Processing
- Compressive Sensing, Sparse Modeling

Multimodal AI

- Multimodal Data Modeling
- Multimodal Data Fusion
- Cross/Multi-modal Learning
- Multimodal Big Data Analytics and Visualization

Applications

- Augmented and Mixed Reality
- Autonomous Driving
- Low-Altitude Visual Perception and Understanding
- Mental Health and Cognitive Stimulation
- Embodied Vision
- Low-level Vision

Tracks

For more information, please visit: www.icvisp.org/tracks.html

Track I :

The Application of Artificial Intelligence in the Field of Meteorology

Track II :

Advances in Hyperspectral Data Analysis and Processing

Key Dates

Abstract Submission Due: August 1, 2026
Registration Due: November 5, 2026

Full Paper Submission Due: August 15, 2026
Camera-ready Submission Due: November 5, 2026

Author Notification Due: October 1, 2026
Main Conference: December 11-13, 2026

Publication

Registered and presented full papers will be included in the ICVISP 2026 digital conference proceedings and submitted to major citation databases (including, but not limited to Ei Compendex and Scopus) for review and indexing.



Publication History

ICVISP 2017 | Osaka, Japan

Published by IEEE
ISBN: 978-1-5386-0612-4
Ei Compendex & Scopus

ICVISP 2020 | Virtually

Published by ACM
ISBN: 978-1-4503-8953-2
Ei Compendex & Scopus

ICVISP 2023 | Dali, China

Published by IET
ISBN: 978-1-83724-014-2
Ei Compendex & Scopus

ICVISP 2018 | Las Vegas, USA

Published by ACM
ISBN: 978-1-4503-6529-1
Ei Compendex & Scopus

ICVISP 2021 | Virtually

Published by IEEE
ISBN: 978-1-6654-0770-0
Ei Compendex & Scopus

IEEE ICVISP 2024 | Kunming, China

Published by IEEE
ISBN: 979-8-3315-4146-0
Ei Compendex & Scopus

ICVISP 2019 | University of British Columbia

Published by ACM
ISBN: 978-1-4503-7625-9
Ei Compendex & Scopus

ICVISP 2022 | Virtually

Published by IOP JPCS
ISSN: 1742-6596
Ei Compendex & Scopus

ICVISP 2025 | Xi'an, China

Published by IEEE
ISBN: 979-8-3315-5682-2
Ei Compendex & Scopus

Submission

- Manuscripts submitted to the conference should be written in English only.
- Manuscripts submitted to the conference should follow the template provided.
- Manuscripts can be submitted in Doc, Docx and PDF format.
- Oral or Poster presentations should be nominated while submitting an abstract.
- The ordinary length is suggested no less than 5 pages, including all figures, tables, references, and appendices. If the paper exceeds 5 pages, the additional pages will be charged at the time of registration.

For paper template, please visit: www.icvisp.org/sub.html

Online Submission link: <https://cmt3.research.microsoft.com/ICVISP2026>

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